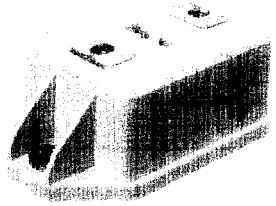


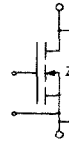
SEMITRANS® M Power MOSFET Modules

SKM 151 F

■ Discontinued 1998



SEMITRANS M1



Features

- N Channel, enhancement mode
- Fast inverse diode
- Short internal connections avoid oscillations
- Switching kW's in less than 1 μ s
- Isolated copper baseplate
- All electrical connections on top for easy busbaring
- Large clearances and creepage distances
- UL recognized, file no. E 63 532

Typical Applications

- Switched mode power supplies
- DC servo and robot drives
- DC choppers
- Resonant and welding inverters
- Induction heaters
- AC motor drives
- Laser power supplies
- UPS equipment
- Plasma cutting
- Not suitable for linear amplification

This is an electrostatic discharge sensitive device (ESDS).

Please observe the international standard IEC 747-1, Chapter IX.

Absolute Maximum Ratings						
Symbol	Conditions ¹⁾		Values	Units		
V_{DS}			500	V		
V_{DGR}	$R_{GS} = 20 \text{ k}\Omega$		500	V		
I_D			56	A		
I_{DM}			224	A		
V_{GS}			± 20	V		
P_D			700	W		
T_j, T_{stg}			$-55 \dots +150$	$^{\circ}\text{C}$		
V_{isot}	AC, 1 min		2 500	V		
humidity	DIN 40 040		Class F			
climate	DIN IEC 68 T.1		55/150/56			
Inverse Diode						
$I_F = -I_D$			56	A		
$I_{FM} = -I_{DM}$			224	A		
Characteristics			min.	typ.	max.	Units
$V_{(BR)DSS}$	$V_{GS} = 0, I_D = 0,25 \text{ mA}$		500	–	–	V
$V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = 1 \text{ mA}$		2,1	3,0	4,0	V
I_{DSS}	$V_{GS} = 0, T_j = 25^{\circ}\text{C}$	$V_{DS} = 500 \text{ V}$	–	50	250	μA
		$T_j = 125^{\circ}\text{C}$	–	300	1000	μA
I_{GSS}	$V_{GS} = 20 \text{ V}, V_{DS} = 0$		–	10	100	nA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}, I_D = 36 \text{ A}$		–	90	110	m Ω
g_{fs}	$V_{DS} = 25 \text{ V}, I_D = 36 \text{ A}$		20	30	–	S
C_{CHC}			–	–	160	pF
C_{iss}	$V_{GS} = 0$ $V_{DS} = 25 \text{ V}$ $f = 1 \text{ MHz}$		–	22	30	nF
C_{oss}			–	1,6	2,4	nF
C_{rss}			–	0,6	1	nF
L_{DS}			–	–	20	nH
$t_{d(on)}$	$V_{DD} = 250 \text{ V}$ $I_D = 36 \text{ A}$ $V_{GS} = 10 \text{ V}$ $R_{GS} = 3,3 \Omega$		–	60	–	ns
t_r			–	35	–	ns
$t_{d(off)}$			–	350	–	ns
t_f			–	70	–	ns
Inverse Diode						
V_{SD}	$I_F = 110 \text{ A}, V_{GS} = 0$		–	1,3	1,6	V
t_{rr}	$T_j = 25^{\circ}\text{C} \text{ } ^2)$ $T_j = 150^{\circ}\text{C} \text{ } ^2)$		–	200	280	ns
			–	350	500	ns
Q_{rr}	$T_j = 25/150^{\circ}\text{C} \text{ } ^2)$		–	1,5/8,5	2,5/12	μC
I_{RRM}	$T_j = 25/150^{\circ}\text{C} \text{ } ^2)$		–	12/28	–	A
Thermal Characteristics						
R_{thjc}			–	–	0,18	$^{\circ}\text{C/W}$
R_{thch}	$M_1, \text{ surface } 10 \text{ }\mu\text{m}$		–	–	0,05	$^{\circ}\text{C/W}$
Mechanical Data						
M_1	to heatsink, SI Units		4	–	6	Nm
	to heatsink, US Units		35	–	53	lb.in.
M_2	for terminals, SI Units		2,5	–	3,5	Nm
	for terminals, US Units		22	–	24	lb.in.
a			–	–	5x9,81	m/s ²
w			–	–	150	g
Case	\rightarrow page B 5 – 2		D 15			

¹⁾ $T_{case} = 25^{\circ}\text{C}$, unless otherwise specified

²⁾ $I_F = -I_D, V_R = 100 \text{ V}, -di_F/dt = 100 \text{ A}/\mu\text{s}$

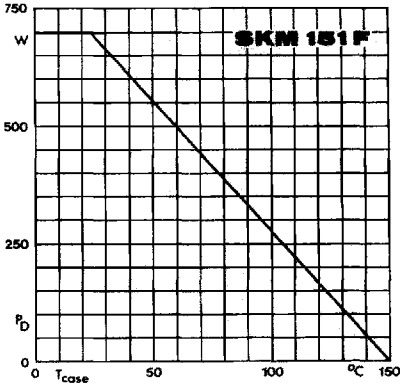


Fig. 1 Rated power dissipation vs. temperature

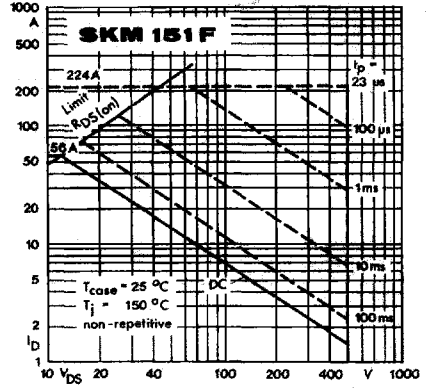


Fig. 2 Maximum safe operating area

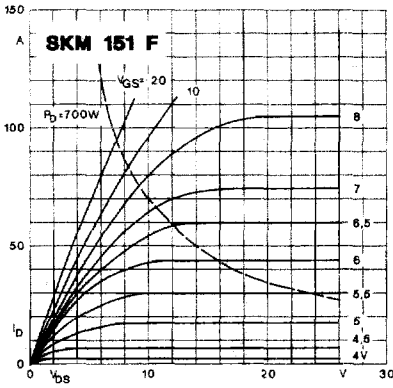


Fig. 3 Output characteristic

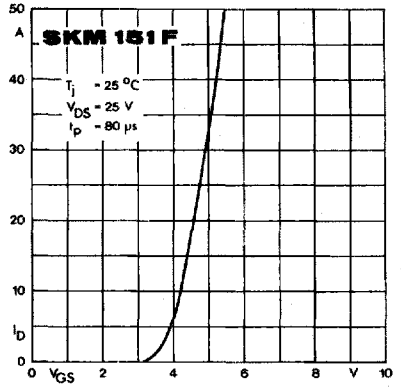


Fig. 4 Transfer characteristic

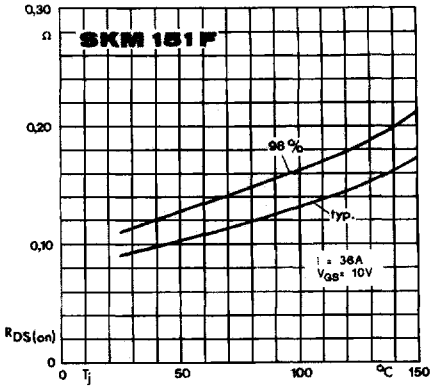


Fig. 5 On-resistance vs. temperature

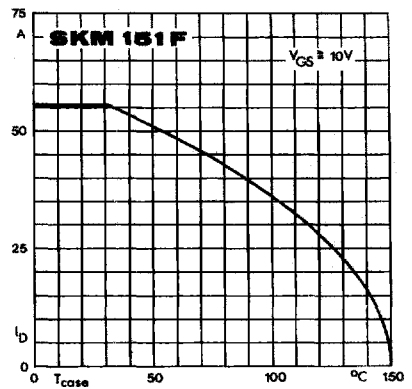


Fig. 6 Rated current vs. temperature

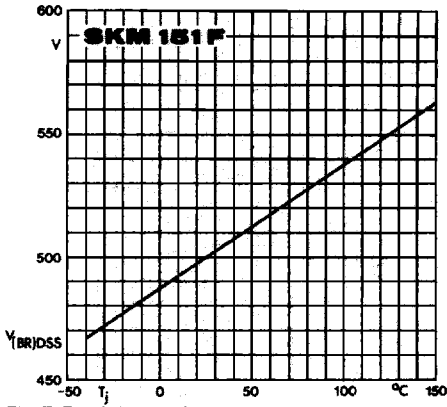


Fig. 7 Breakdown voltage vs. temperature

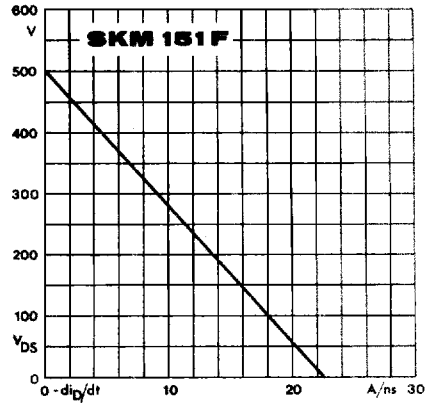


Fig. 8 Drain-source voltage derating

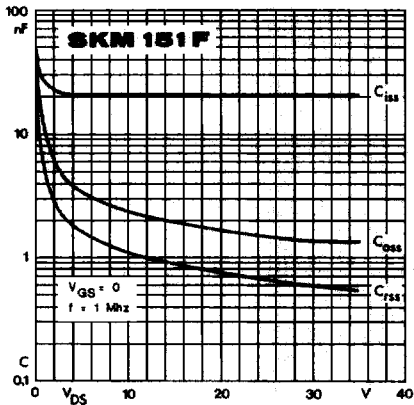


Fig. 9 Capacitances vs. drain-source voltage

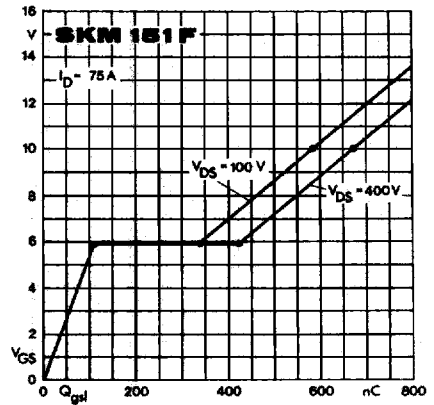


Fig. 10 Gate charge characteristic

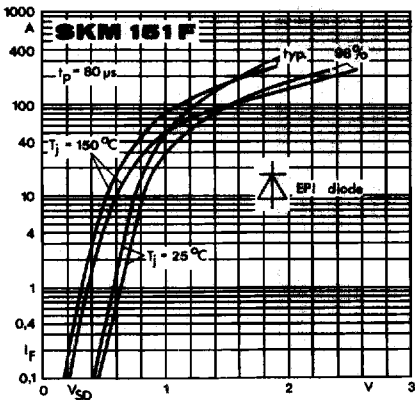


Fig. 11 Diode forward characteristic

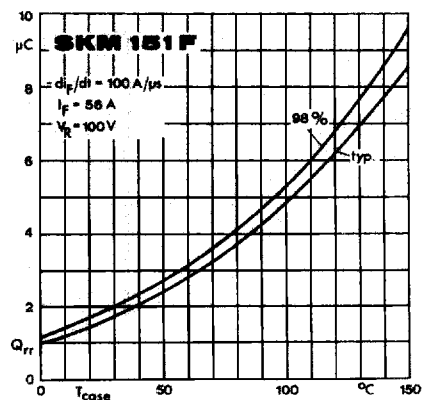


Fig. 12 Diode recovered charge

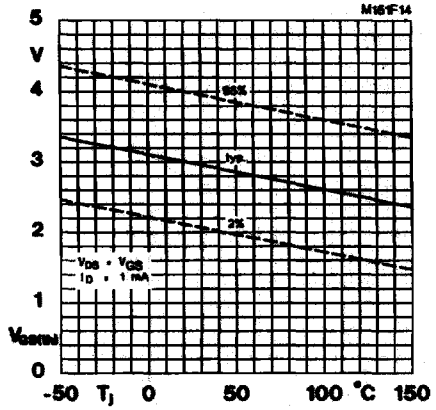


Fig. 14 Gate-source threshold voltage

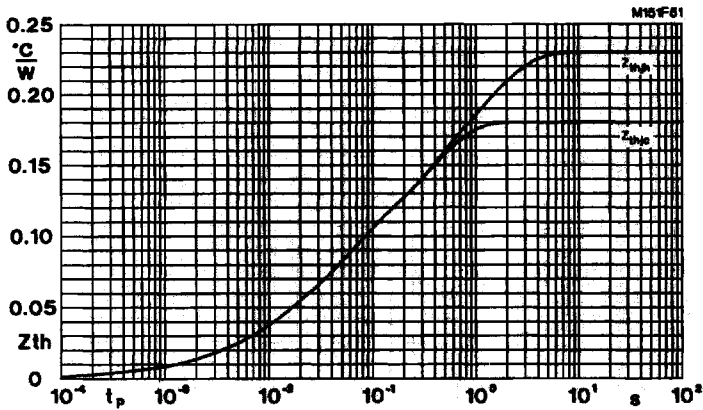


Fig. 51 Transient thermal impedance

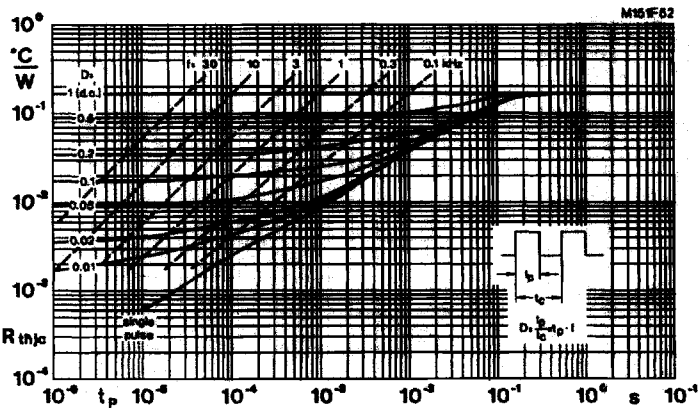


Fig. 52 Thermal impedance under pulse conditions